RECOMMENDED PCB LAYOUT FOR HDTF-3-XX-X-RA-XX-XXX REVISION C 12/19/2023 ECN-472772 **DESIGNED & DIMENSIONED** IN MILLIMETERS[INCHES] Ø0.36±0.05[.014±.002] PTH— ◆ 0.10 X Y Ø0.450±0.130[.0177±.005] (DRILLED HOLE) $+ \phi 0.75 \pm 0.13 [.030 \pm .01] (PAD)$ -Y-0.68 [.027] REF **SEE NOTE 4** 8.0 [.31] REF 10.7 [.42] REF (SEE NOTE 5) 10.7 [.42] REF (SEE NOTE 5) **COPPER** (SEE NOTE 5) (SEE TABLE 2 & NOTE 2) 'A'-(SEE TABLE 2) HOLE PLATING DETAIL SCALE 12:1 ₩ 働 .382 (3 PLCS)-**(** ¦ф 0 0 **((** (1) 0 0 0 0 (11) **(** 7.20 .283 • 0 0 0 0 (11) 1.240 ! 0 0 0 0 .197 (0) 15.9 [.63] REF 0 0 0 (11) 3.80 .150 0 (SEE NOTE 5) **(** 3.60 .142 .094 • 0 0 0 0 .098 **(** 1.30 .051 **(** 0 0 0 0 (0) 11.40|||.055| 0.20 .008 0 0 (H) (11) (0) (0) FIG 1 26.0[1.02] REF -X-0 0 (11) .047 (HDTF-3-06-X-RA-XX-XXX FOOTPRINT SHOWN) (SEE NOTE 1) 3.80 [.150] (0) 0 0 2.30 0.91 MAX 1.50[.059] REF 3 5 6 (FRONT EDGE OF PCB) (SEE NOTE 4) TABLE 1 -SIGNAL A 1 13.90 [.547] REF COLUMNS "A" 7.2 [0.28] CONNECTOR OUTLINE -06 10.8 [0.43] (SEE NOTE 1) -08 14.4 [0.57] TABLE 2 "A" REF Cu 0.025-0.050 [.0010-.0020] TIN (IMMERSION) (SEE NOTE 1 & 5) 0.001-0.002 [.00004-.00008] Sn 0.025-0.050 [.0010-.0020] NI **ENIG** Au 0.000076-0.000254 [.000003-.000010] NOTES: С OSP Cu 0.025-0.050 [.0010-.0020]

- 1. CONNECTOR ENVELOPE DIMENSION. OTHER COMPONENTS PLACED ON PCB SHALL AVOID THIS ZONE.
 2. COPPER PLATING THICKNESS MAY NOT VARY BY MORE THAN 0.02[.001] WITHIN ANY VIA.
 3. CONTACT SAMTEC FOR CONNECTOR PRESS FIT INSTRUCTIONS AND REQUIRED FIXTURES.
 4. 1.10[.043] MIN BOARD THICKNESS FOR .450[0.0177] DRILL.
 5. USE KEEPOUT AREA FOR CONNECTOR REPAIR.

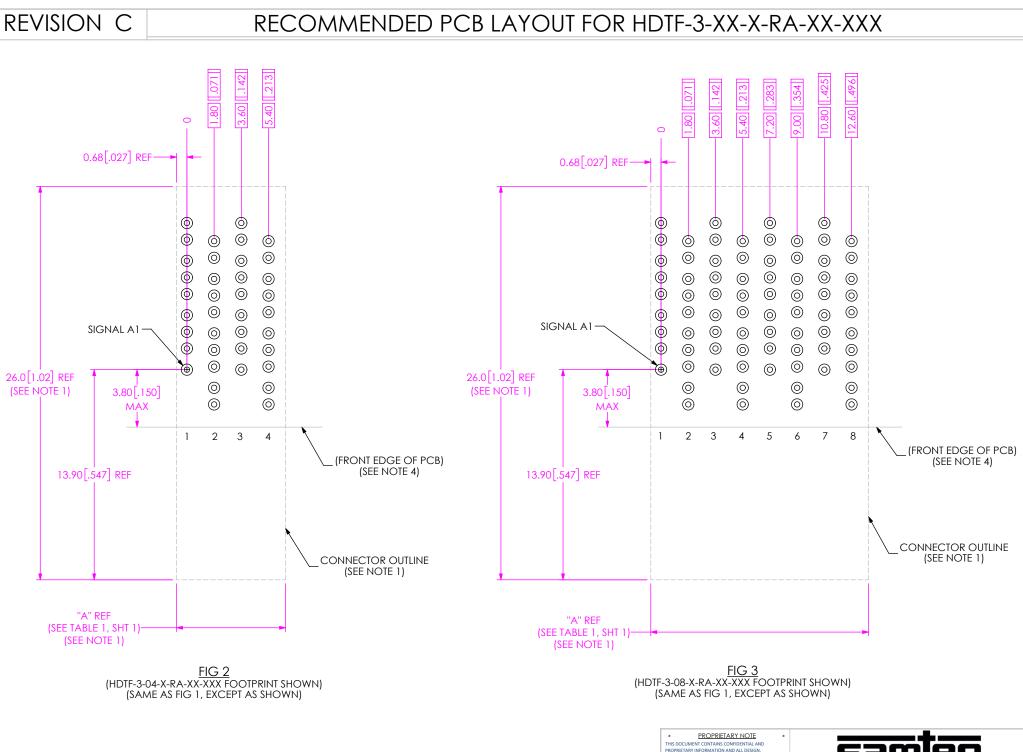
- 6. FOR -HS OPTION, ALL GROUNDS WITHIN A COLUMN ARE COMMON.

PROPRIETARY NOTE THIS DOCUMENT CONTAINS CONFIDENTIAL AND PROPRIETARY INFORMATION AND ALL DESIGN MANUFACTURING, REPRODUCTION, USE, PATENT RIGHTS AND SALES RIGHTS ARE EXPRESSLY RESERVED BY SAMTEC, INC. THIS DOCUMENT SHALL NOT BE DISCLOSED, IN WHOLE OR PART, TO ANY UNAUTHORIZED PERSON OR ENTITY NOF REPRODUCED, TRANSFERRED OR INCORPORATED IN ANY OTHER PROJECT IN ANY MANNER WITHOUT THE EXPRESS

WRITTEN CONSENT OF SAMTEC, INC.



520 PARK EAST BLVD, NEW ALBANY, IN 47150 PHONE: 812-944-6733 FAX: 812-948-5047 e-Mail info@SAMTEC.com code 55322

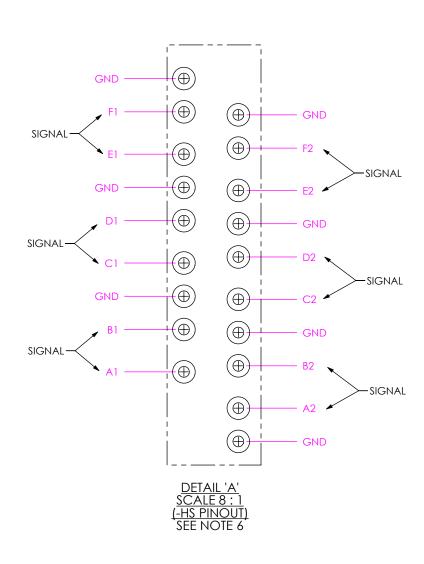


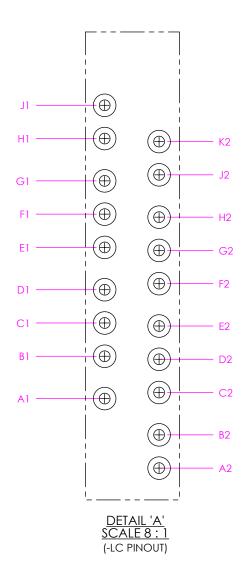
MANUFACTURING, REPRODUCTION, USE, PATENT RIGHTS AND SALES RIGHTS ARE EXPRESSLY RESERVED BY SAMTEC, INC. THIS DOCUMENT SHALL NOT BE DISCLOSED, IN WHOLE OR PART, TO ANY UNAUTHORIZED PERSON OR ENTITY NOR REPRODUCED, TRANSFERRED OR INCORPORATED IN ANY

OTHER PROJECT IN ANY MANNER WITHOUT THE EXPRESS

WRITTEN CONSENT OF SAMTEC, INC.

RECOMMENDED PCB LAYOUT FOR HDTF-3-XX-X-RA-XX-XXX





* PROPRIETARY NOTE THIS DOCUMENT CONTAINS CONFIDENTIAL AND

PROPRIETARY INFORMATION AND ALL DESIGN, MANUFACTURING, REPRODUCTION, USE, PATENT RIGHTS AND SALES MIGHTS ARE LOPAGES, YEARSTEED BY SAMITEC, INC. THIS DOCUMENT SHALL NOT BE DISCLOSED, IN WHOLE OF PART, TO AN UNAUTHORIZED PERSON DE ENTITY MOR REPRODUCED, TRANSFERRED OR INCORPORATED IN ANY OTHER PROJECT IN ANY MANNER WITHOUT THE EXPRESS WRITTEN CONSENT OF SAMITEC, INC.



e-Mail info@SAMTEC.com

code 55322